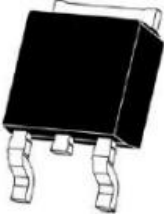

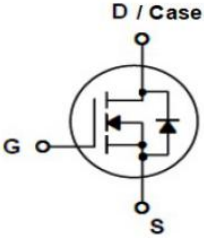




Description

<p>Product Summary</p> <ul style="list-style-type: none"> • VDS 100V • ID 45A • RDS(ON) (at VGS=10V) < 17 mohm • RDS(ON) (at VGS=4.5V) < 21.5 mohm • 100% UIS Tested • 100% ∇VDS Tested 	<p>General Description</p> <ul style="list-style-type: none"> • Low RDS(on) & FOM • Extremely low switching loss • Excellent stability and uniformity • Fast switching and soft recovery <p>Applications</p> <ul style="list-style-type: none"> • Power switching application • Hard switched and high frequency circuits • Uninterruptible power supply
<p>Package</p> <div style="display: flex; justify-content: space-around; align-items: center;">    </div> <p style="text-align: center;">TO-252</p>	

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Limit	Unit
VDS	Drain-source Voltage	100	V
VGS	Gate-source Voltage	±20	V
ID	Drain Current	T _C =25°C	45
		T _C =100°C	28.5
IDM	Pulsed Drain Current ^A	130	A
EAS	Avalanche energy ^B	110	mJ
PD	Total Power Dissipation ^C	T _c =25°C	72
		T _c =100°C	28.8
T _J , T _{STG}	Junction and Storage Temperature Range	-55~+150	°C

Thermal resistance

Symbol	Parameter	Typ	Max	Units
R _{θJA}	Thermal Resistance Junction-to-Ambient ^D	t ≤ 10S	15	°C/W
	Thermal Resistance Junction-to-Ambient ^D	Steady-State	40	
R _{θJC}	Thermal Resistance Junction-to-Case	Steady-State	1.35	1.7



45N10(文件编号: S&CIC1904)

N-Channel Trench Power MOSFET

Electrical Characteristics ($T_j=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Static Parameter						
BVDSS	Drain-Source Breakdown Voltage	VGS= 0V, ID=250 μ A	100			V
IDSS	Zero Gate Voltage Drain Current	VDS=100,VGS=0V			1	μ A
IGSS	Gate-Body Leakage Current	GS= \pm 20V, VDS=0V			\pm 100	nA
VGS(th)	Gate Threshold Voltage	VDS= VGS, ID=250 μ A	1	1.8	3	V
RDS(ON)	Static Drain-Source On-Resistance	VGS= 10V, ID=20A		14	17	m Ω
		VGS= 4.5V, ID=20A		17.5	21.5	m Ω
VSD	Diode Forward Voltage	IS=20A,VGS=0V			1.3	V
IS	Maximum Body-Diode Continuous Current				45	A
RG	Gate resistance	f= 1 MHz, Open drain		1		Ω
Dynamic Parameters						
Ciss	Input Capacitance	VDS=50V,VGS=0V,f=1MHZ		1135		pF
Coss	Output Capacitance			399		
Crss	Reverse Transfer Capacitance			18		
Switching Parameters						
Qg	Total Gate Charge	VGS=10V,VDS=50V,ID=25A		16		nC
Qgs	Gate-Source Charge			5.6		
Qgd	Gate-Drain Charge			2.4		
Qrr	Reverse Recovery Charge	IF=20A, di/dt=100A/us		42		ns
trr	Reverse Recovery Time			39.8		
tD(on)	Turn-on Delay Time	VGS=10V, VDD=50 ,ID=25A RGEN=2.2 Ω		39.2		ns
tr	Turn-on Rise Time			11		
tD(off)	Turn-off Delay Time			53.2		
tf	Turn-off fall Time			15.8		

- A. Repetitive rating; pulse width limited by max. junction temperature.
- B. $V_{DD}=20\text{V}$, $R_G=25\Omega$, $L=0.5\text{mH}$, $I_{AS}=20\text{A}$.
- C. Pd is based on max. junction temperature, using junction-case thermal resistance.
- D. The value of RqJA is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The Power dissipation PDSM is based on R qJA \leq 10s and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.



Typical Performance Characteristics

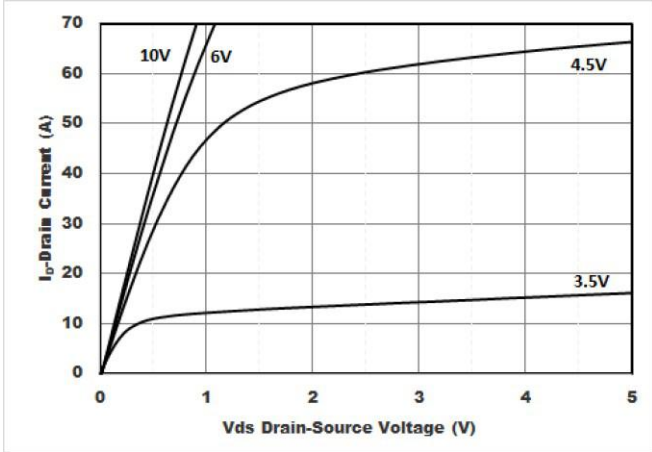


Figure1. Output Characteristics

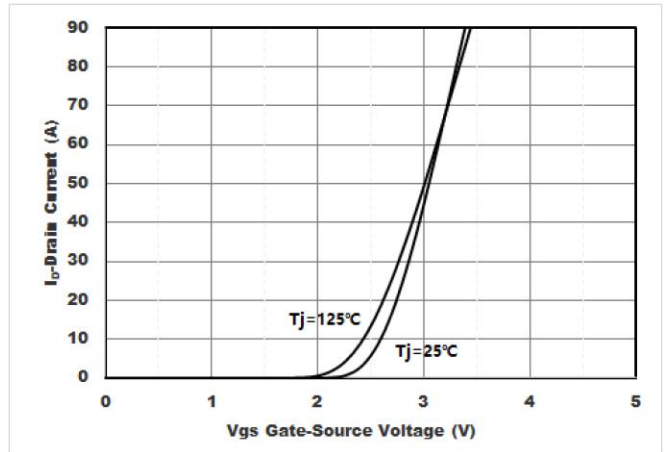


Figure2. Transfer Characteristics

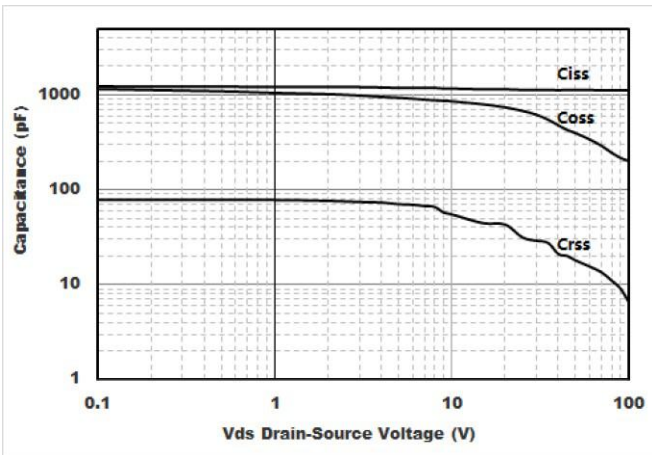


Figure3. Capacitance Characteristics

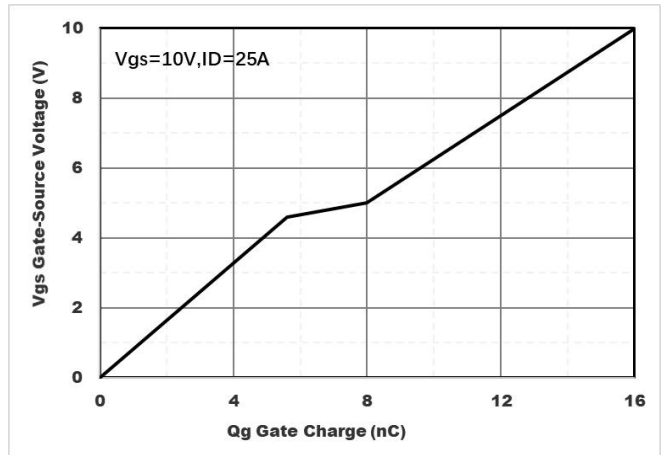


Figure4. Gate Charge

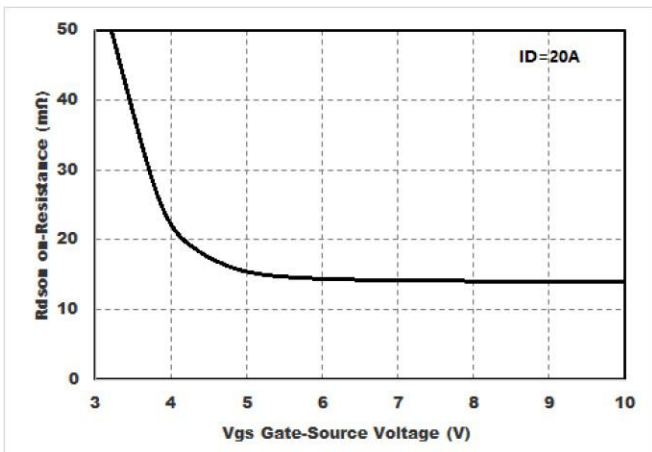


Figure5. : On-Resistance vs. Drain Current and Gate Voltage

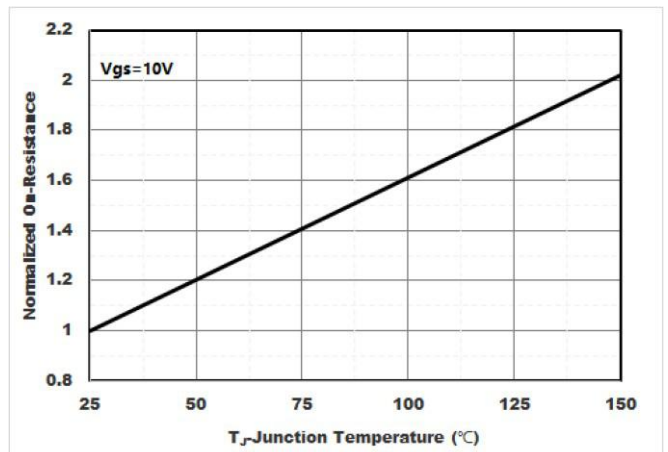


Figure6. Normalized On-Resistance

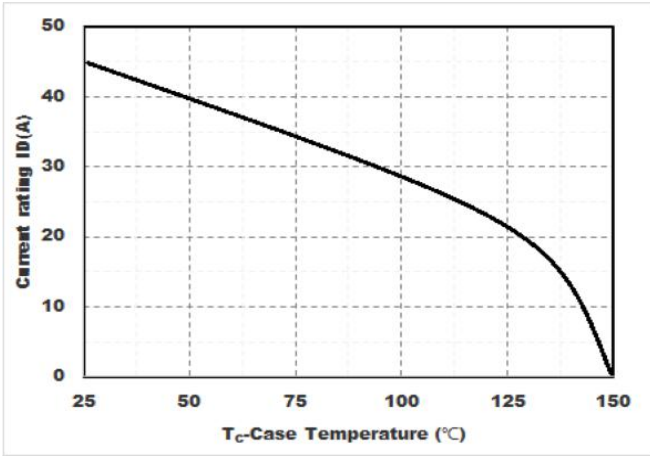


Figure7. Drain current

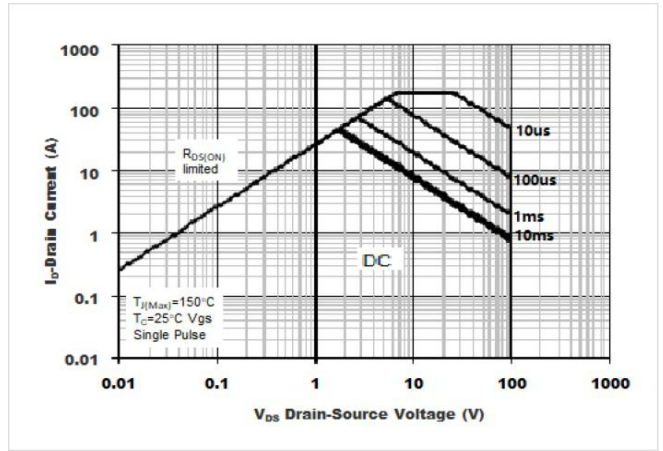


Figure8.Safe Operation Area

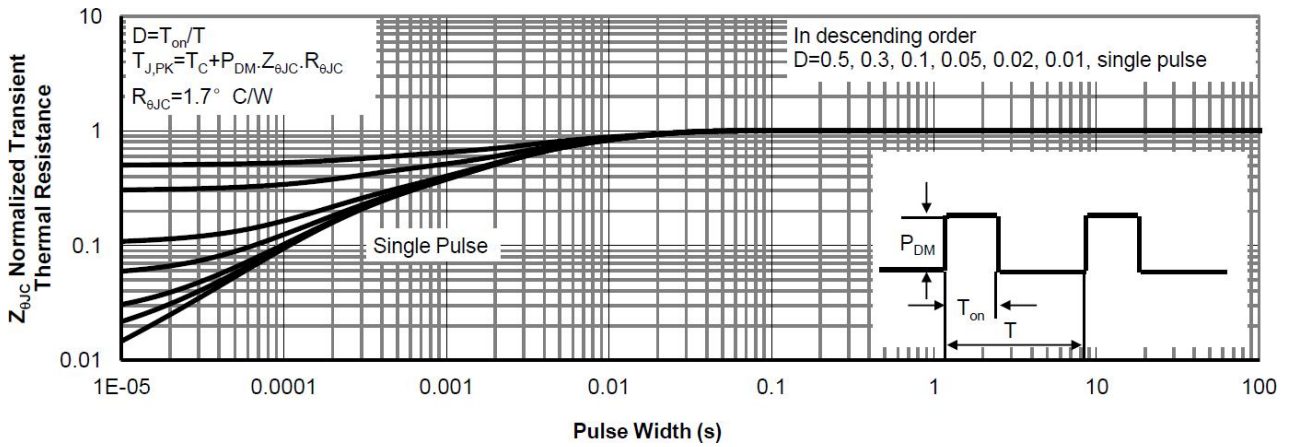


Figure9.Normalized Maximum Transient thermal impedance

Test Circuit

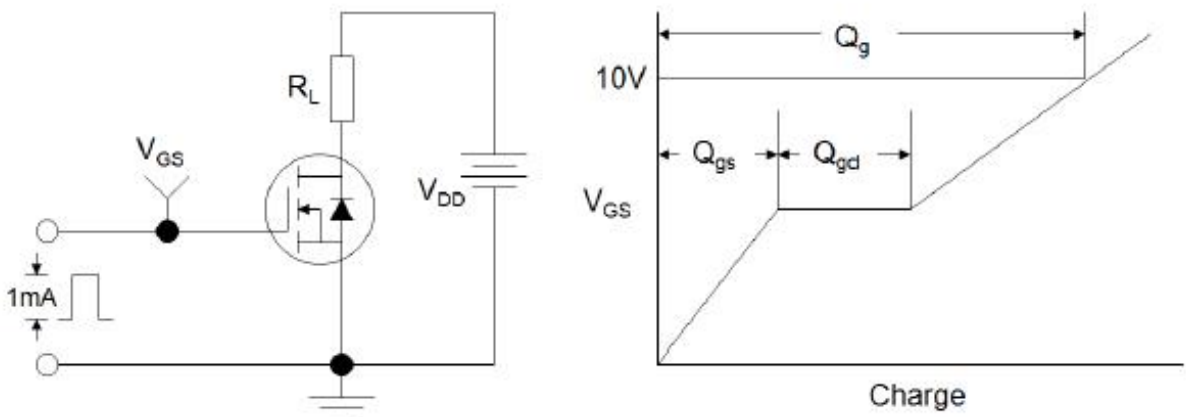


Figure1:Gate Charge Test Circuit & Waveform

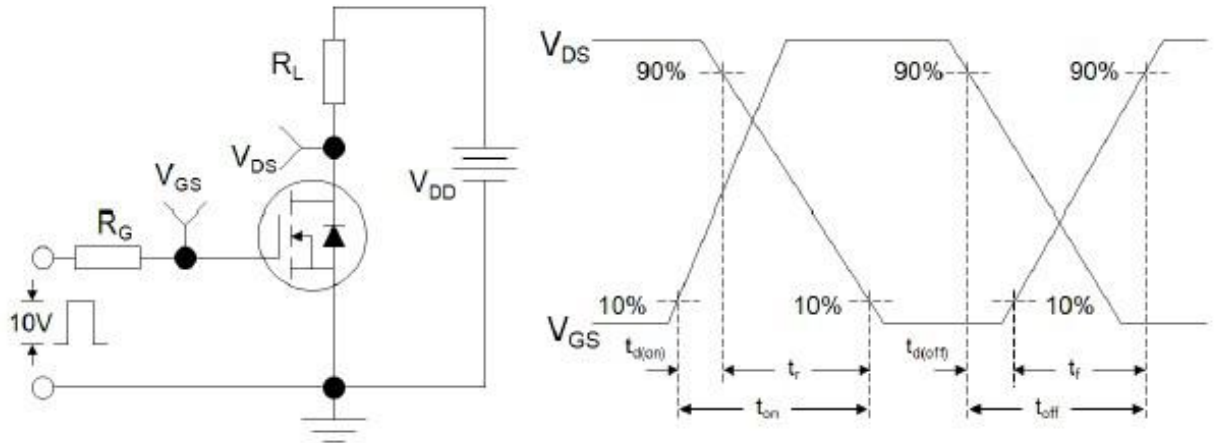


Figure 2: Resistive Switching Test Circuit & Waveforms

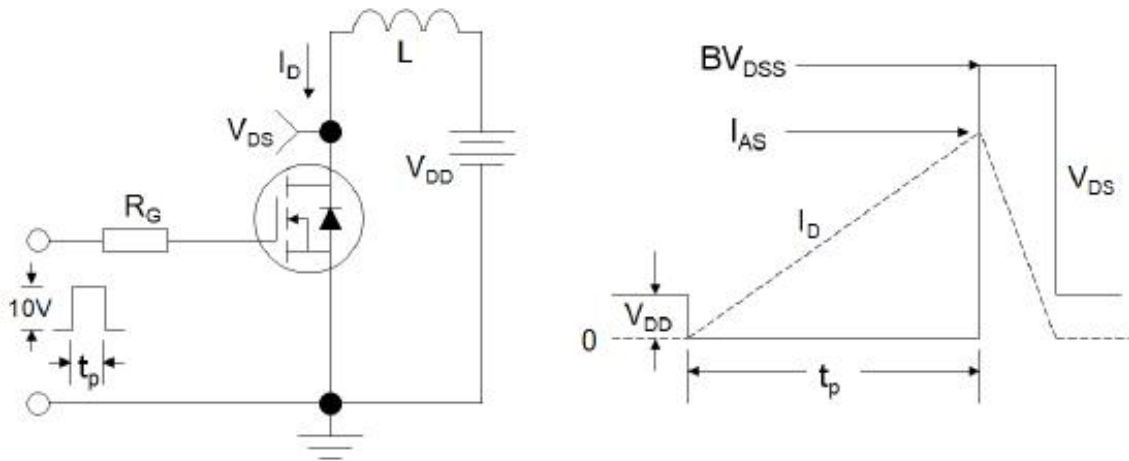
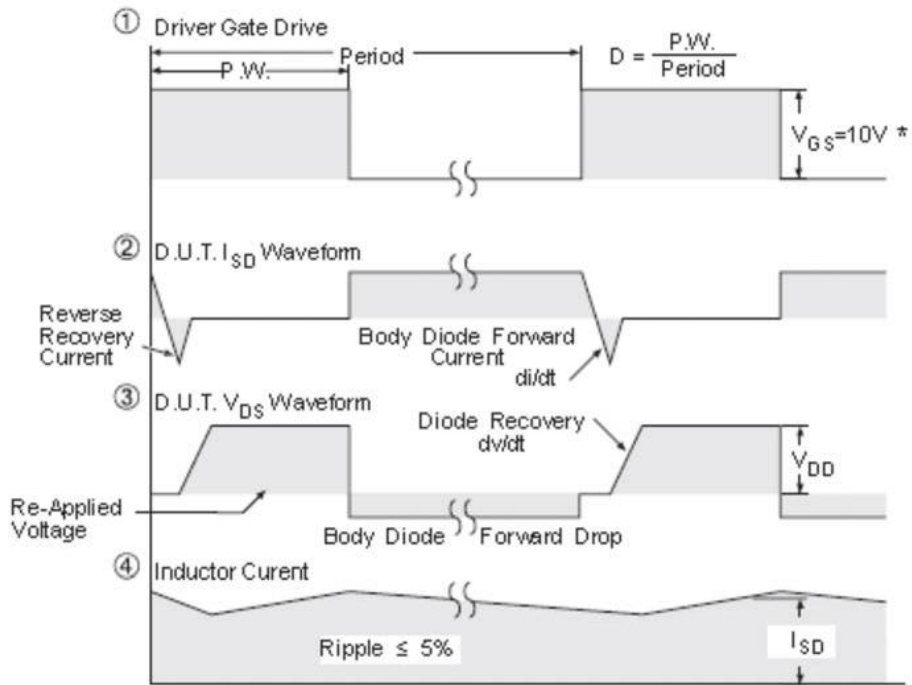
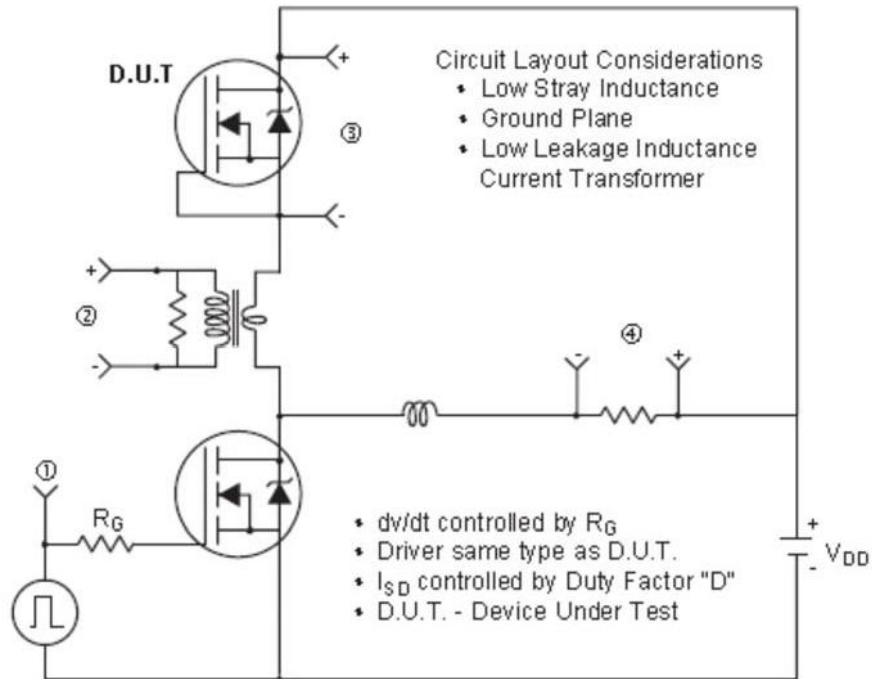


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms

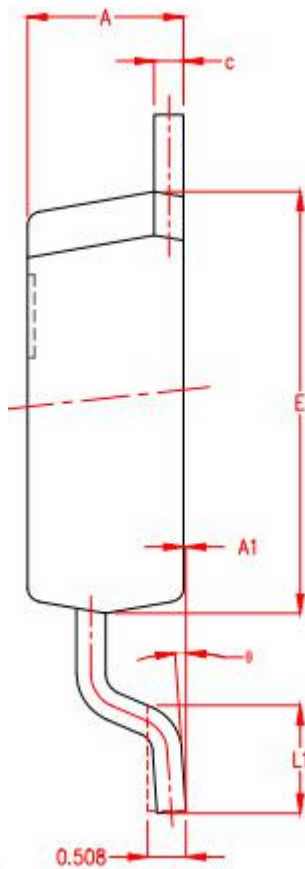
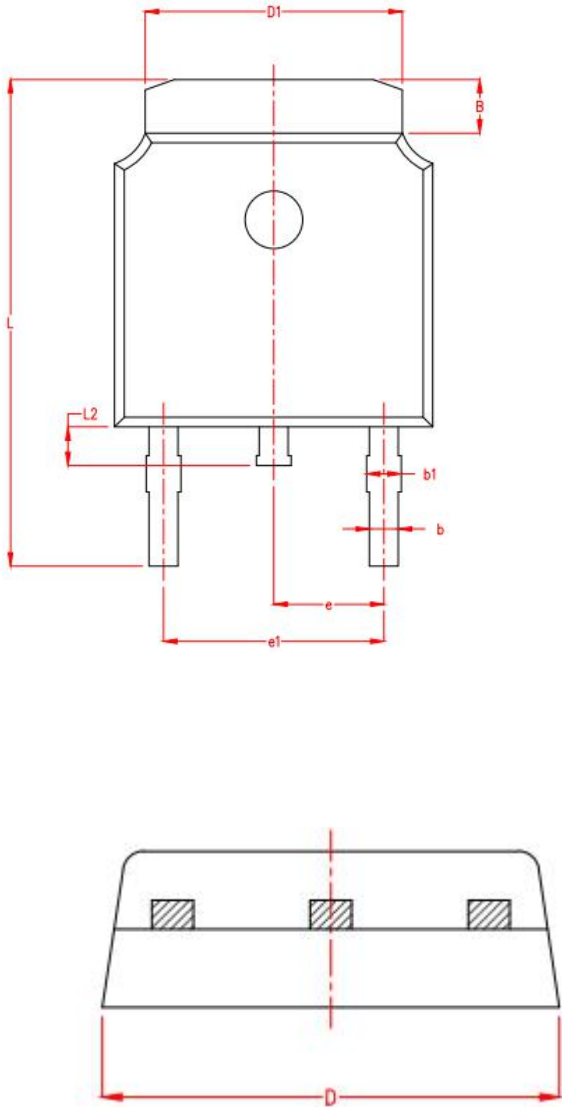


* $V_{GS} = 5V$ for Logic Level Devices

Figure 4: Peak Diode Recovery dv/dt Test Circuit & Waveforms (For N-channel)



TO-252 Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.15	2.25	2.35
A1	0.00	0.06	0.12
B	0.96	1.11	1.26
b	0.59	0.69	0.79
b1	0.69	0.81	0.93
c	0.34	0.42	0.50
D	6.45	6.60	6.75
D1	5.23	5.33	5.43
E	5.95	6.10	6.25
e	2.286TYP.		
e1	4.47	4.57	4.67
L	9.90	10.10	10.30
L1	1.40	1.55	1.70
L2	0.60	0.80	1.00
θ	0°	4°	8°